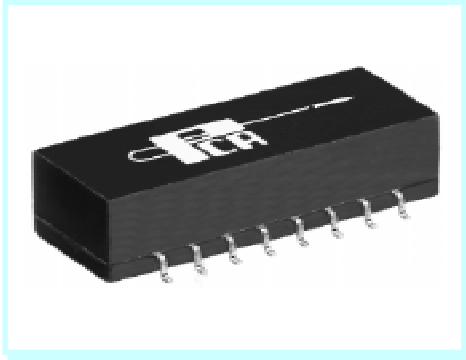


## EPF8046G



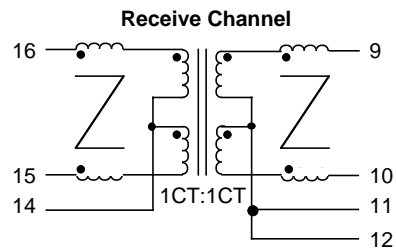
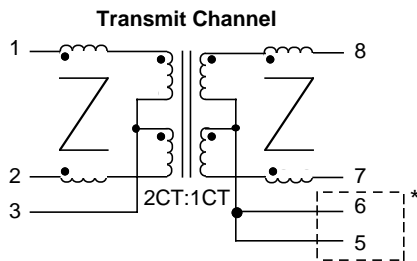
- Optimized to work with ML6692/94 PHY chip •
- Guaranteed to operate with 8 mA DC bias at 70°C on cable side •
- Complies with or exceeds IEEE 802.3, 100 BX Standards •
- Robust construction allows for most severe soldering processes •

### Electrical Parameters @ 25° C

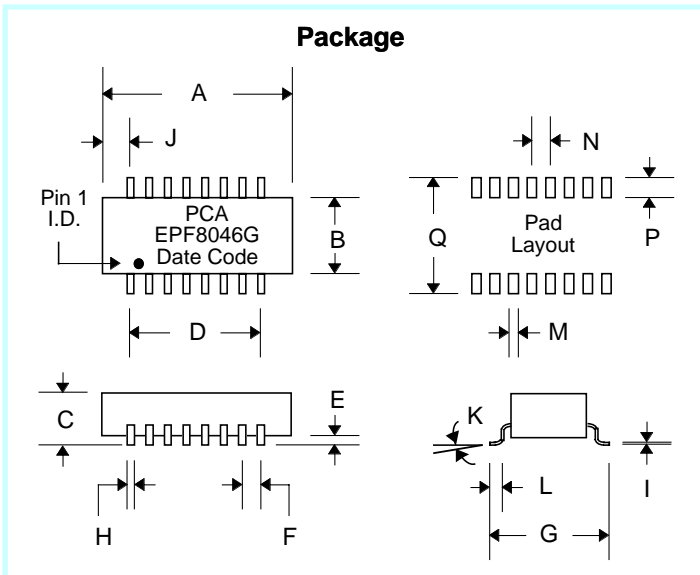
OCL @ 70°C	Insertion Loss (dB Max.)		Return Loss (dB Min.)						Common Mode Rejection (dB Min.)				Crosstalk (dB Min.) [Between Channels]		
	100 KHz, 0.1 Vrms 8 mA DC Bias	1-100 MHz	1-20 MHz		60 MHz		80 MHz		30-100 MHz		200 MHz			500 MHz	
Cable Side	Xmit	Rcv	Xmit	Rcv	Xmit	Rcv	Xmit	Rcv	Xmit	Rcv	Xmit	Rcv	Xmit	Rcv	
350µH	-1	-1	-18	-25	-8	-20	-6	-20	-30	-30	-25	-25	-20	-15	-40

• Isolation : 1500 Vrms • Cable Impedance : 100 Ω • Rise Time : 3.0 nS Max. • \*Optional •

### Schematic



### Package



### Dimensions

Dim.	(Inches)			(Millimeters)		
	Min.	Max.	Nom.	Min.	Max.	Nom.
A	.970	.990		24.64	25.15	
B	.380	.400		9.65	10.16	
C	.223	.243		5.66	6.17	
D	.700	Typ.		17.78	Typ.	
E	.003	.020		0.076	.508	
F	.100	Typ.		2.54	Typ.	
G	.500	.520		12.7	13.20	
H	.016	.022		.406	.559	
I	.008	.012		.203	.305	
J	.090	Typ.		2.28	Typ.	
K	0°	8°		0°	8°	
L	.025	.045		.635	1.14	
M			.030			.762
N			.100			2.54
P			.092			2.34
Q			.560			14.22

## EPF8046G

The circuit below is a guideline for interconnecting PCA's EPF8046G with ML6692 or ML6694 chip applications. Further details can be obtained from the chip manufacturer application notes.

Typical insertion loss of the isolation transformer is 0.5dB. This parameter covers the entire spectrum of the encoded signals in 100 BX protocol. Under terminated conditions, to transmit a 2V pk-pk signal across the cable, you must adjust the chips supporting resistor to get at least 2.12V pk-pk across the transmit pins.

Note that in the 100 BX application, you do not need a split primary. The reason is that there is no 10 Base-T to negotiate. The receiver side can be terminated as shown or a by single 100 Ω with primary center tap taken to ground via a suitable cap.

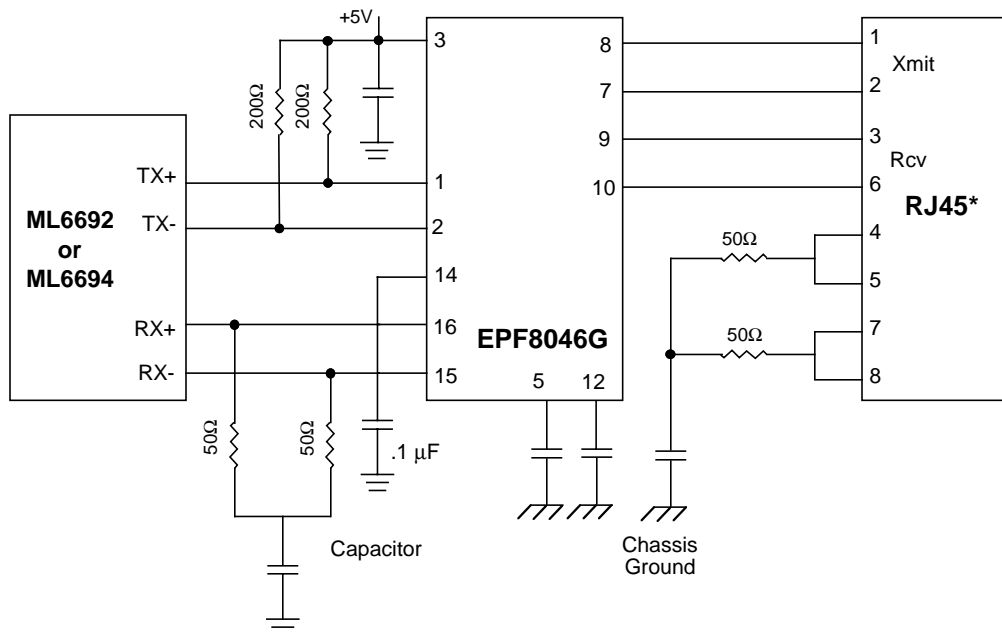
The phantom resistors shown around the connector have been known to suppress unwanted radiation that unused wires pick up from the immediate environment. Their placement and use are to be considered carefully before a design is finalized.

Also, in, some cases, there has been EMI improvement by taking pin 12 to Chassis via a cap. It may not be required: this can be decided only during an EMC test. Same comments apply to pin 5 connection.

It is recommended that there be a neat separation of ground planes in the layout. It is generally accepted practice to limit the plane off at least 0.05 inches away from the chip side pins of EPF8046G. There need not be any ground plane beyond this plane.

For best results, PCB designer should design the outgoing traces preferably to be 50 Ω, balanced and well coupled to achieve minimum radiation from these traces.

### Typical Application Circuit for UTP



Notes : \* NIC Side is shown. Hub side connection will swap pins 3-6 with 1-2.